

## General Description

The MY003BBNE3 is the highest performance trench N-ch MOSFETS with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the small power switching and load switch applications.

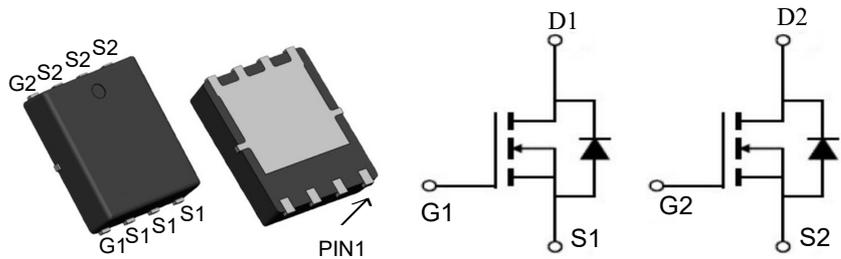


## Features

$V_{DSS}$	20	V
$I_D$	80	A
$R_{DS(ON)}$ (at $V_{GS} = 10V$ )	5	m $\Omega$
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$ )	9	m $\Omega$

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY003BBNE3	PDFN3*3-8	3350	5000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	80	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	50	A
$I_D@T_A=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	30	A
$I_D@T_A=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	15	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	100	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation <sup>1</sup>	31	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation <sup>1</sup>	3.6	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	35	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	4	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =3A	---	1.5	2.5	mΩ
		V <sub>GS</sub> =3.9V , I <sub>D</sub> =3A	---	2.5	3.5	
		V <sub>GS</sub> =2.5V , I <sub>D</sub> =3A	---	5	7	
		V <sub>GS</sub> =1.8V , I <sub>D</sub> =3A	---	9	10	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.4	---	1.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25 °C	---	---	1	uA
		V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55 °C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ± 8V , V <sub>DS</sub> =0V	---	---	± 10	uA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =3A	---	42	---	S
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =10V , I <sub>D</sub> =3A	---	38	---	nC
	Total Gate Charge (3.9V)		---	33	---	
Q <sub>gs</sub>	Gate-Source Charge		---	4.5	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	12	---	
T <sub>d(on)</sub>	Turn-On Delay Time		V <sub>DD</sub> =16V , V <sub>GS</sub> =4.5V , R <sub>G</sub> =6 I <sub>D</sub> =3A	---	22	
T <sub>r</sub>	Rise Time	---		41	---	
T <sub>d(off)</sub>	Turn-Off Delay Time	---		77	---	
T <sub>f</sub>	Fall Time	---		21	---	
C <sub>iSS</sub>	Input Capacitance	V <sub>DS</sub> =10V , V <sub>GS</sub> =0V , f=1MHz	---	1200	---	pF
C <sub>oss</sub>	Output Capacitance		---	193	---	
C <sub>rSS</sub>	Reverse Transfer Capacitance		---	185	---	
I <sub>S</sub>	Continuous Source Current <sup>1</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	30	A
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>		---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =3A , T <sub>J</sub> =25 °C	---	---	1.2	V

**Note :**

1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t ≤10s.

2.The data tested by pulsed , pulse width ≤ 10us , duty cycle ≤ 1%

Typical Characteristics

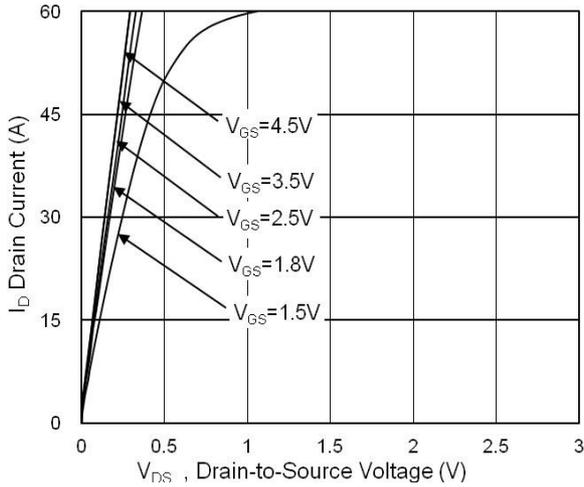


Fig.1 Typical Output Characteristics

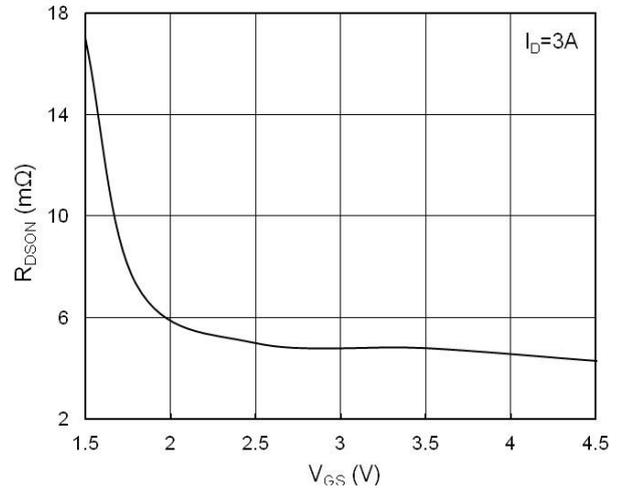


Fig.2 On-Resistance vs. Gate-Source

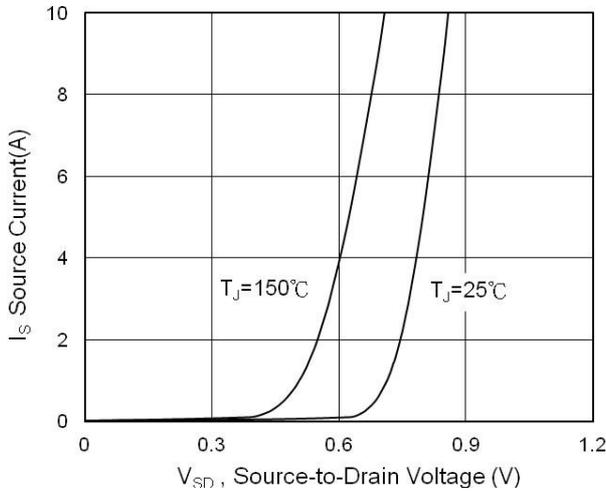


Fig.3 Forward Characteristics Of Reverse

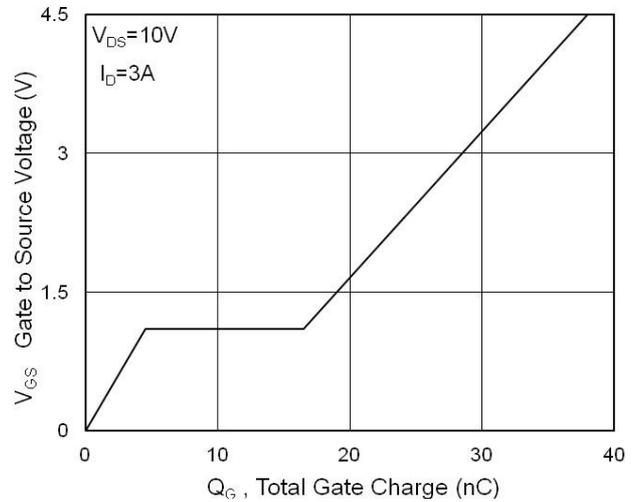


Fig.4 Gate-Charge Characteristics

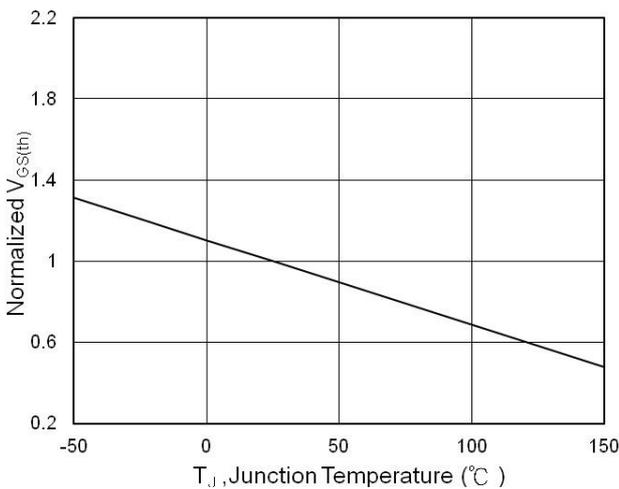


Fig.5  $V_{GS(th)}$  vs.  $T_J$

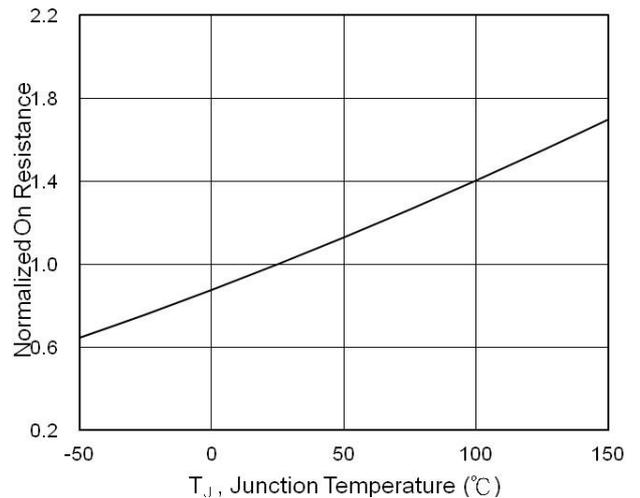


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

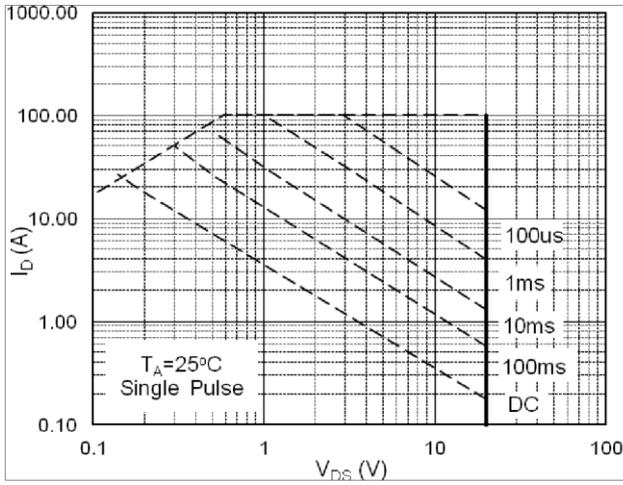


Fig.7 Capacitance

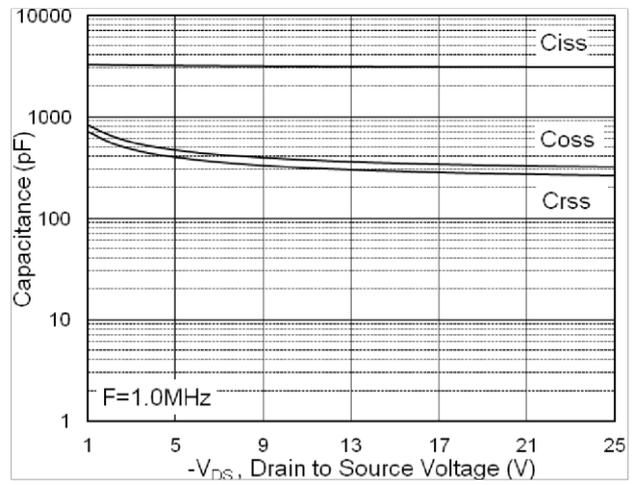


Fig.8 Safe Operating Area

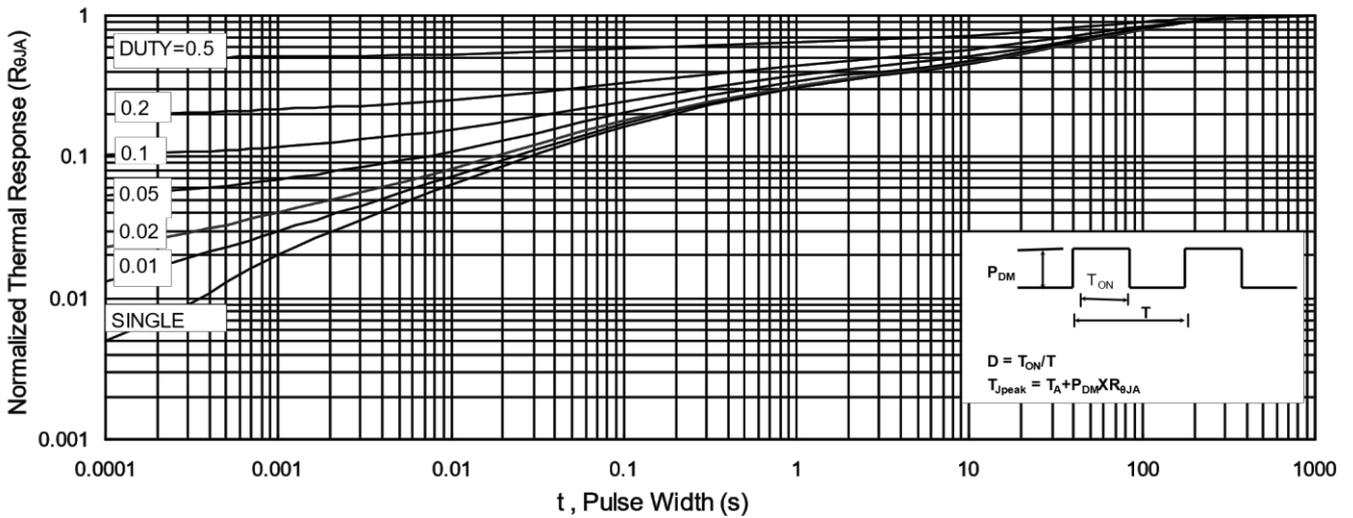


Fig.9 Normalized Maximum Transient Thermal Impedance

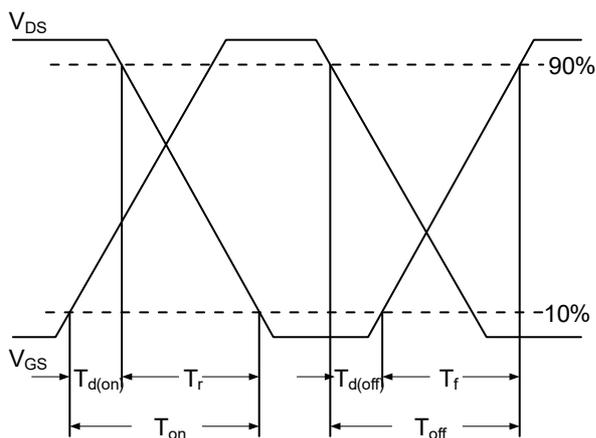


Fig.10 Switching Time Waveform

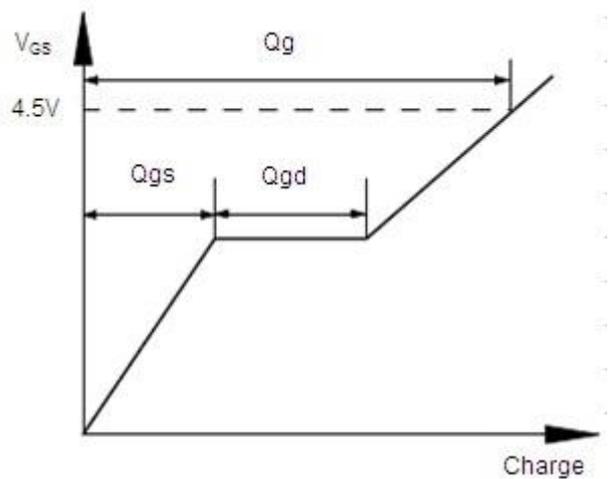
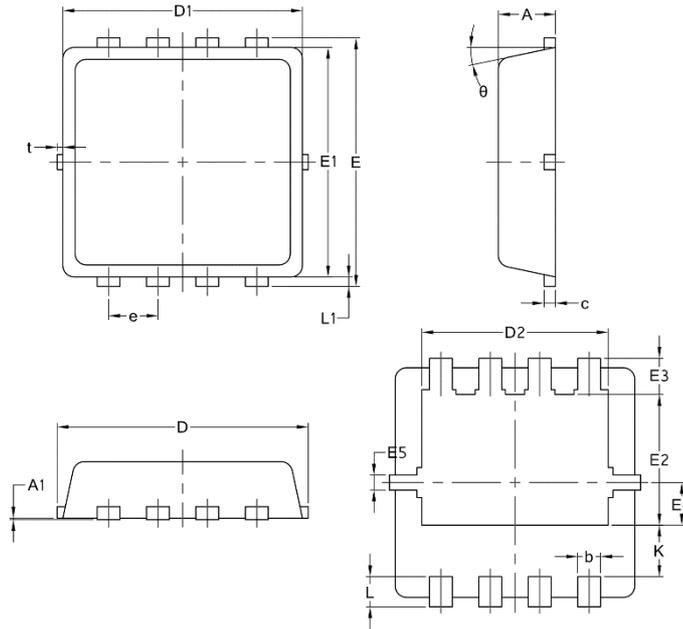


Fig.11 Gate Charge Waveform

**Package Mechanical Data-DFN3\*3-8L-JQ Single**



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14